**Product data sheet** 

# 1. General description

High voltage, high speed NPN planar-passivated power switching transistor in a SOT78 plastic package intended for use in high frequency electronic lighting ballast applications

### 2. Features and benefits

- Fast switching
- High voltage capability of 700 V
- Low thermal resistance

## 3. Applications

· Electronic lighting ballasts

### 4. Quick reference data

### Table 1. Quick reference data

Symbol	Parameter	Conditions	Values		Unit	
Absolute	maximum rating					
V <sub>CESM</sub>	peak collector-emitter voltage	V <sub>BE</sub> = 0 V	700			V
I <sub>c</sub>	collector current (DC)	DC; <u>Fig. 1</u> ; <u>Fig. 2</u> ; <u>Fig. 4</u>	4			Α
P <sub>tot</sub>	total power dissipation	T <sub>mb</sub> ≤ 25 °C; <u>Fig. 3</u>	75			W
Symbol	Parameter	Conditions	Min Typ Max		Max	Unit
Static ch	aracteristics					
h <sub>FE</sub>	DC current gain	I <sub>C</sub> = 1 A; V <sub>CE</sub> = 5 V; T <sub>mb</sub> = 25 °C; Fig. 11	12	20	40	
		I <sub>C</sub> = 2 A; V <sub>CE</sub> = 5 V; T <sub>mb</sub> = 25 °C; Fig. 11	10	17	28	

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# 5. Pinning information

**Table 2. Pinning information** 

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	В	base	mb	С
2	С	collector		j
3	Е	emitter		В —
mb	С	mounting base; connected to collector		E sym123

# 6. Ordering information

**Table 3. Ordering information** 

3							
Type number	Package						
	Name	Description	Version				
PHE13005	TO-220AB	plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB	SOT78				

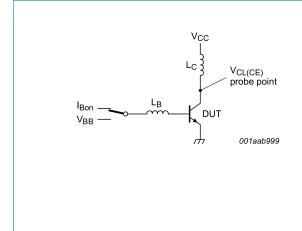
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# 7. Limiting values

### **Table 4. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Values	Unit
V <sub>CESM</sub>	peak collector-emitter voltage	V <sub>BE</sub> = 0 V	700	V
V <sub>CBO</sub>	collector-base voltage	I <sub>E</sub> = 0 A	700	V
V <sub>CEO</sub>	collector-emitter voltage	I <sub>B</sub> = 0 A	400	V
Ic	collector current	DC; Fig. 1; Fig. 2; Fig. 4	4	А
I <sub>CM</sub>	peak collector current		8	А
I <sub>B</sub>	base current	DC	2	А
I <sub>BM</sub>	peak base current		4	А
P <sub>tot</sub>	total power dissipation	T <sub>mb</sub> ≤ 25 °C; <u>Fig. 3</u>	75	W
T <sub>stg</sub>	storage temperature		-65 to 150	°C
T <sub>j</sub>	junction temperature		150	°C
V <sub>EBO</sub>	emitter-base voltage	I <sub>C</sub> = 0 A	9	V



$$\begin{split} &V_{\text{CL(CE)}} \! \leq 1000 \text{V}; \ V_{\text{CC}} = 150 \text{ V}; \ V_{\text{BB}} = \text{-}5 \text{ V}; \\ &L_{\text{C}} = 200 \ \mu\text{H}; \ L_{\text{B}} = 1 \ \mu\text{H} \end{split}$$



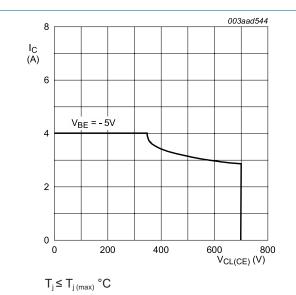


Fig. 2. Reverse bias safe operating area

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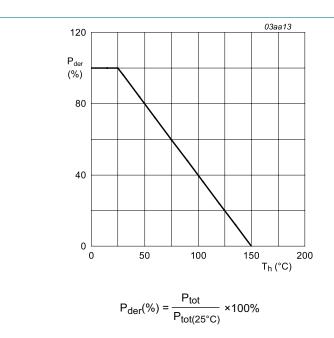
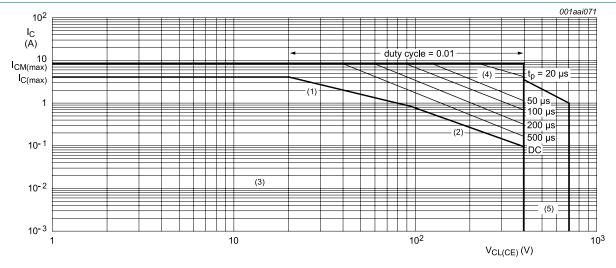


Fig. 3. Normalized total power dissipation as a function of heatsink temperature



 $T_h \le 25 \,^{\circ}C$ 

Mounted with heatsink compound and  $(30 \pm 5)$  N force on the centre of the envelope

- (1) P<sub>tot</sub> maximum and P<sub>tot</sub> peak maximum lines
- (2) Second breakdown limits
- (3) Region of permissible DC operation
- (4) Extension of operating region for repetitive pulse operation
- (5) Extension of operating region during turn-on in single transistor converters provided that  $R_{BE} \le 100~\Omega$  and  $t_p \le 0.6~\mu s$

Fig. 4. Forward bias safe operating area

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### 8. Thermal characteristics

**Table 5. Thermal characteristics** 

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R <sub>th(j-mb)</sub>	thermal resistance from junction to mounting base	<u>Fig. 5</u>	-	-	1.67	K/W
$R_{\text{th(j-a)}}$	thermal resistance from junction to ambient	in free air	-	60	-	K/W

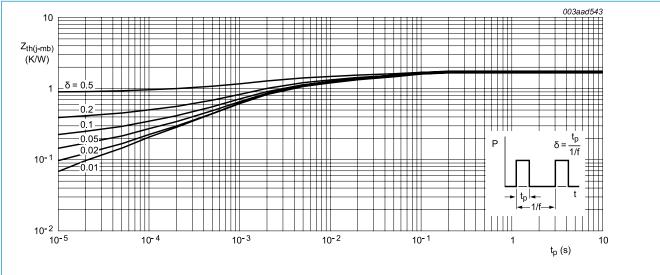


Fig. 5. Transient thermal impedance from junction to mounting base as a function of pulse duration

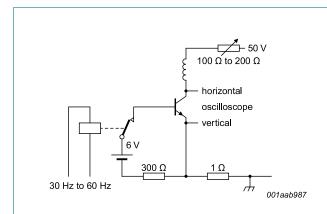
Silicon diffused power transistor

## 9. Characteristics

### **Table 7. Characteristics**

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static cha	aracteristics					
I <sub>CES</sub>	collector-emitter cut-off	$V_{BE} = -1.5 \text{ V}; V_{CE} = 700 \text{ V}; T_{mb} = 25 \text{ °C}$	-	-	1	mA
	current	V <sub>BE</sub> = -1.5 V; V <sub>CE</sub> = 700 V; T <sub>j</sub> = 125 °C	-	-	5	mA
I <sub>CBO</sub>	collector-base cut-off current	$V_{CB} = 700 \text{ V}; I_E = 0 \text{ A}; T_{mb} = 25 \text{ °C}$	-	-	1	mA
I <sub>CEO</sub>	collector-emitter cut-off current	$V_{CEO} = 400 \text{ V}; I_{B} = 0 \text{ A}; T_{mb} = 25 \text{ °C}$	-	-	0.1	mA
I <sub>EBO</sub>	emitter-base cut-off current	$V_{EB} = 9 \text{ V}; I_{C} = 0 \text{ A}; T_{mb} = 25 \text{ °C}$	-	-	1	mA
$V_{CEOsus}$	collector-emitter sustaining voltage	$I_B = 0 \text{ A}; I_C = 10 \text{ mA}; L_C = 25 \text{ mH};$ $T_{mb} = 25 \text{ °C}; \underline{\text{Fig. 6}}; \underline{\text{Fig. 7}}$	400	-	-	V
V <sub>CEsat</sub>	collector-emitter saturation voltage	$I_{C}$ = 1.0 A; $I_{B}$ = 0.2 A; $T_{mb}$ = 25 °C; Fig. 8; Fig. 9	-	0.1	0.5	V
		$I_C = 2.0 \text{ A}; I_B = 0.5 \text{ A}; T_{mb} = 25 \text{ °C};$ Fig. 8; Fig. 9	-	0.2	0.6	V
		$I_C = 4.0 \text{ A}; I_B = 1.0 \text{ A}; T_{mb} = 25 \text{ °C};$ Fig. 8; Fig. 9	-	0.3	1	V
$V_{BEsat}$	base-emitter saturation voltage	$I_C = 1.0 \text{ A}; I_B = 0.2 \text{ A}; T_{mb} = 25 \text{ °C};$ Fig. 10	-	0.85	1.2	V
		$I_C = 2.0 \text{ A}; I_B = 0.5 \text{ A}; T_{mb} = 25 \text{ °C};$ Fig. 10	-	0.92	1.6	V
h <sub>FE</sub>	DC current gain	$I_C = 1 \text{ A}; V_{CE} = 5 \text{ V}; T_{mb} = 25 ^{\circ}\text{C};$ Fig. 11	12	20	40	
		$I_C = 2 \text{ A}; V_{CE} = 5 \text{ V}; T_{mb} = 25 \text{ °C};$ Fig. 11	10	17	28	
Dynamic	characteristics					
t <sub>s</sub>	storage time	$I_{C}$ = 2 A; $I_{Bon}$ = 0.4 A; $I_{Boff}$ = -0.4 A; $R_{L}$ = 75 $\Omega$ ; $T_{mb}$ = 25 °C; resistive load; Fig. 12; Fig. 13	-	2.7	4	μs
		$I_{C}$ = 2 A; $I_{Bon}$ = 0.4 A; $V_{BB}$ = -5 V; $L_{B}$ = 1 $\mu$ H; $T_{mb}$ = 25 °C; inductive load; <u>Fig. 14</u> ; <u>Fig. 15</u>	-	1.2	2	μs
		$I_{C}$ = 2 A; $I_{Bon}$ = 0.4 A; $V_{BB}$ = -5 V; $L_{B}$ = 1 $\mu$ H; $T_{mb}$ = 100 °C; inductive load; <u>Fig. 14</u> ; <u>Fig. 15</u>	-	1.4	4	μs
t <sub>f</sub>	fall time	$I_{C}$ = 2 A; $I_{Bon}$ = 0.4 A; $I_{Boff}$ = -0.4 A; $R_{L}$ = 75 $\Omega$ ; $T_{mb}$ = 25 °C; resistive load; Fig. 12; Fig. 13	-	0.3	0.9	μs
		$I_{C}$ = 2 A; $I_{Bon}$ = 0.4 A; $V_{BB}$ = -5 V; $L_{B}$ = 1 $\mu$ H; $T_{mb}$ = 25 °C; inductive load; <u>Fig. 14</u> ; <u>Fig. 15</u>	-	0.1	0.5	μs
		$I_{C}$ = 2 A; $I_{Bon}$ = 0.4 A; $V_{BB}$ = -5 V; $L_{B}$ = 1 $\mu$ H; $T_{mb}$ = 100 °C; inductive load; Fig. 14; Fig. 15	-	0.16	0.9	μs

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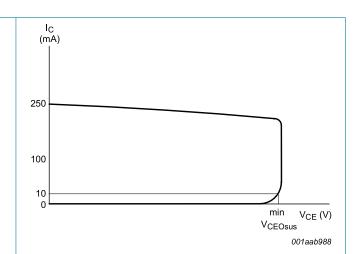
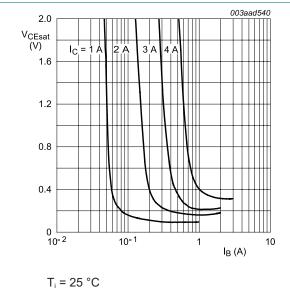


Fig. 6. Test circuit for collector-emitter sustaining voltage

Fig. 7. Oscilloscope display for collector-emitter sustaining voltage test waveform



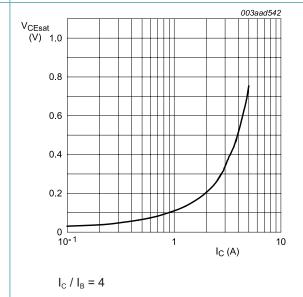


Fig. 8. Collector-emitter saturation voltage; typical values

Fig. 9. Collector-emitter saturation voltage as a function of collector current; typical values

### Silicon diffused power transistor

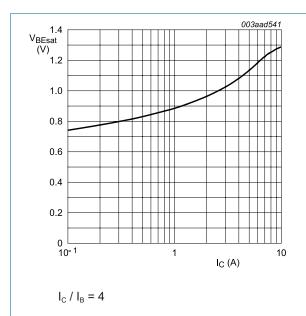
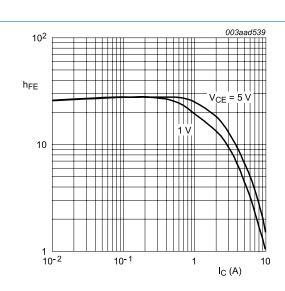
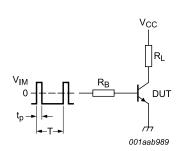


Fig. 10. Base-emitter saturation voltage; typical values



T<sub>j</sub> = 25 °C
Fig. 11. DC current gain as a function of collector current; typical values



 $V_{IM} = -6 \text{ to } + 8 \text{ V}; V_{CC} = 250 \text{ V}; t_p = 20 \text{ } \mu\text{s}; \\ \delta = t_p / T = 0.01$ 

 $R_B$  and  $R_L$  calculated from  $I_{Con}$  and  $I_{Bon}$  requirements.



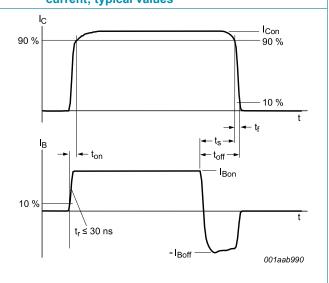
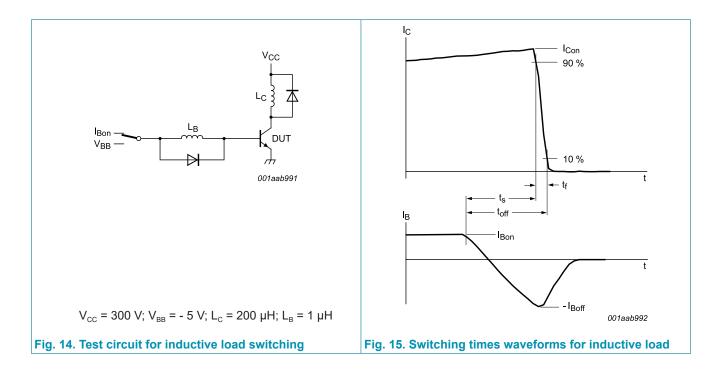


Fig. 13. Switching times waveforms for resistive load

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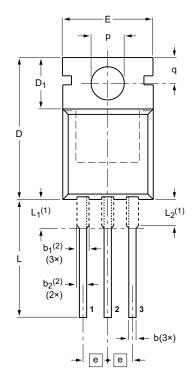


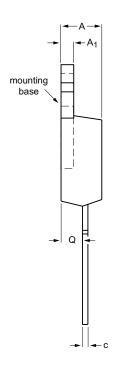
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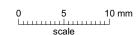
# 10. Package outline

Plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB

**SOT78** 







### **DIMENSIONS** (mm are the original dimensions)

UNIT	А	A <sub>1</sub>	b	b <sub>1</sub> <sup>(2)</sup>	b <sub>2</sub> <sup>(2)</sup>	С	D	D <sub>1</sub>	E	е	L	L <sub>1</sub> <sup>(1)</sup>	L <sub>2</sub> <sup>(1)</sup> max.	р	q	Q
mm	4.7 4.1	1.40 1.25	0.9 0.6	1.6 1.0	1.3 1.0	0.7 0.4	16.0 15.2	6.6 5.9	10.3 9.7	2.54	15.0 12.8	3.30 2.79	3.0	3.8 3.5	3.0 2.7	2.6 2.2

### Notes

- 1. Lead shoulder designs may vary.
- 2. Dimension includes excess dambar.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT78		3-lead TO-220AB	SC-46			<del>08-04-23</del> 08-06-13

### Silicon diffused power transistor

### 11. Legal information

#### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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